



FPC REINFORCEMENT MATERIALS

LOCTITE® ECCOBOND DS 3318LV AND LOCTITE® ECCOBOND EN 3410

Henkel's LOCTITE® ECCOBOND DS 3318LV and LOCTITE ECCOBOND EN 3410 are designed for reinforcement of OLED, Chip-on-Glass (COG) and flexible printed circuit (FPC) module coating applications for LCDs. Both materials deliver high-humidity reliability performance, can be cured with UV, visible or LED light, and offer strong reinforcement even for OLED devices with large, thin screens. LOCTITE ECCOBOND DS 3318LV and LOCTITE ECCOBOND EN 3410 are halogen-free materials with high flexibility to support bending and folding. Low water vapor transmission rates (WVTR) provide good barrier protection. The combination of reliability and flexibility enables manufacturers to realize high-yield, cost-effective production for profitable results.





KEY BENEFITS

- Fast cure
- Low viscosity
- · High adhesion to polyimide and glass
- Good moisture resistance
- Excellent flexibility with high elongation capabilities



PRODUCT PROPERTIES

PRODUCT		LOCTITE ECCOBOND DS 3318LV	LOCTITE ECCOBOND EN 3410
DESCRIPTION		High-reliability, highly flexible reinforcement material	Low modulus, fast UV-cure version of LOCTITE ECCOBOND DS 3318LV
TYPICAL APPLICATION		COG, FPC, and panel reinforcement	COG, FPC, and panel reinforcement
PROPERTIES BEFORE CURE	APPEARANCE	Light yellow, transparent liquid	Light yellow
	VISCOSITY AT 15 s ⁻¹ (cP)	968	680
PROPERTIES AFTER CURE	GLASS TRANSITION TEMPERATURE, T _g (°C)	64	67
	TENSILE MODULUS (MPa)	250	100
	ELONGATION AT BREAK (%)	> 150	> 200
	WATER VAPOR TRANSMISSION RATE, WVTR, AT 0.3 mm THICK (g/[m²-day])	< 20	<20
	SODIUM AND CHLORIDE ION IMPURITY (ppm)	<10	<10
	PEEL STRENGTH ON POLYIMIDE SUBSTRATE (N/cm)	> 3.3	>5



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